

Name:

Student Number:

Quiz 4 ELEC 4705
Tuesday Nov. 28 2013

1. (15 marks) IC Fabrication

(a) What is photolithography? (5 Marks)

- What is the primary goal?

The primary goal is the transfer of patterns or images to the surface of the wafer.

- Describe the three basic steps in photolithography.

- i. Deposition (spinning/coating) of photoresist on the surface of the wafer.**
- ii. Exposure of the photoresist to an optical image.**
- iii. Developing of the image in the photoresist.**

(b) Describe the basic procedure to create an opening of SiO_2 on a wafer and create a metal contact. (10 Marks)

- i. How do we create the oxide layer?

One of:

- A. thermal oxidation**
- B. physical deposition (sputtering)**
- C. chemical deposition (CVD)**

- ii. How do we create the contact cut in the oxide?

We use photolithography to define the cut and then use etching.

- iii. Why might we dope the Si under the cut heavily?

To obtain a ohmic contact.

- iv. What is a method by which we could deposit the metal?

Sputtering or CVD

- v. How would we pattern the metal layer?

We use photolithography to define the lines/contacts and then use etching to remove the metal we don't want.

2. (8 Marks) Nano-technology and MEMS

- (a) Why are electron microscopes used as basic tools in nano-technology and not optical microscopes?

The minimum resolution obtainable in imaging tools is determined by the wavelength of the field (optical or electron). Nano-structures are much smaller than the wavelength of light so it can not be used to image them

- (b) What do we mean by “self-assembly”?

Self-assembly is the spontaneous organization of objects (molecules, atoms, polymers) into a structured assembly – showing some pattern, periodicity or preferential orientation.

- (c) Why do objects such as molecules self-assemble into organized structures?

To minimize their total energy.

- (d) What is the technique that we use to form “free” structures such as rotating gears in MEMS devices?

We use a “sacrificial layer”. A layer of material is deposited to allow for the creation of a final structure (including parts that may be “free”). This layer is later removed by etching to release the structure.